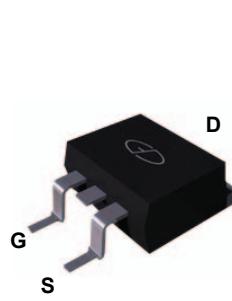
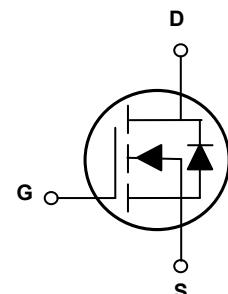


Main Product Characteristics

| | |
|--------------|-------|
| V_{DS} | 60V |
| $R_{DS(ON)}$ | 4.0mΩ |
| I_D | 150A |



TO-263(D²PAK)



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFT06150 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|---|--------------------------|-------------|---------------------------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 150 | A |
| Drain Current-Continuous($T_C=100^\circ\text{C}$) | $I_D(100^\circ\text{C})$ | 105 | A |
| Pulsed Drain Current | I_{DM} | 600 | A |
| Maximum Power Dissipation | P_D | 220 | W |
| Derating Factor | | 1.47 | W/ $^\circ\text{C}$ |
| Single Pulse Avalanche Energy ⁵ | E_{AS} | 900 | mJ |
| Thermal Resistance, Junction-to-Case ² | $R_{\theta JC}$ | 0.68 | $^\circ\text{C}/\text{W}$ |
| Operating Junction Temperature Range | T_J | -55 To +175 | $^\circ\text{C}$ |
| Storage Temperature Range | T_{STG} | -55 To +175 | $^\circ\text{C}$ |

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|--|----------------------------|--|------|-------|-----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 60 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 100 | nA |
| On Characteristics³ | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 2 | 3 | 4 | V |
| Drain-Source On-State Resistance | $R_{\text{DS(ON)}}$ | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=75\text{A}$ | - | 3.1 | 4.0 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=10\text{V}, I_{\text{D}}=75\text{A}$ | - | 80 | - | S |
| Dynamic Characteristics⁴ | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | - | 5451 | - | PF |
| Output Capacitance | C_{oss} | | - | 609 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 488 | - | |
| Switching Characteristics⁴ | | | | | | |
| Total Gate Charge | Q_g | $V_{\text{DS}}=30\text{V}, I_{\text{D}}=75\text{A}, V_{\text{GS}}=10\text{V}$ | - | 130.8 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 22.8 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 56.9 | - | |
| Turn-On Delay Time | $t_{\text{d(on)}}$ | $V_{\text{DD}}=30\text{V}, R_{\text{L}}=0.4\Omega, V_{\text{GS}}=10\text{V}, R_{\text{G}}=2.5\Omega$ | - | 25 | - | nS |
| Turn-On Rise Time | t_r | | - | 23 | - | |
| Turn-Off Delay Time | $t_{\text{d(off)}}$ | | - | 90 | - | |
| Turn-Off Fall Time | t_f | | - | 38 | - | |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Current ² | I_s | | - | - | 150 | A |
| Diode Forward Voltage ³ | V_{SD} | $I_s=75\text{A}, V_{\text{GS}}=0\text{V}$ | - | - | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $T_j=25^\circ\text{C}, I_{\text{F}}=75\text{A}$ $di/dt=-100\text{A}/\mu\text{s}^3$ | - | 60 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 80 | - | nC |
| Forward Turn-On Time | t_{on} | Intrinsic turn-on is negligible(turn-on is dominated by LS+LD) | | | | |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_j=25^\circ\text{C}, V_{\text{DD}}=30\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_{\text{G}}=25\Omega$

Typical Electrical and Thermal Characteristic Curves

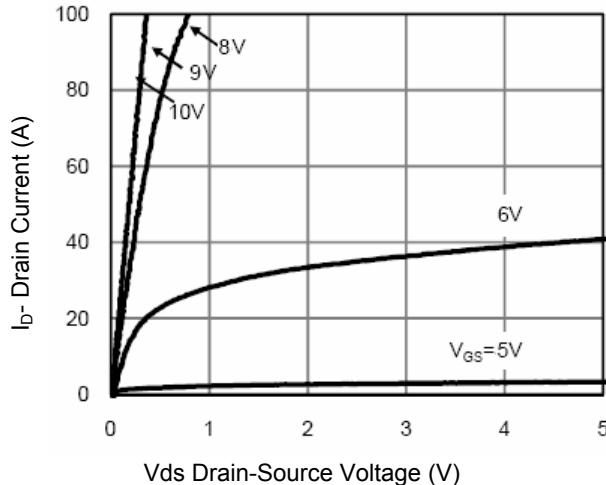


Figure 1. Output Characteristics

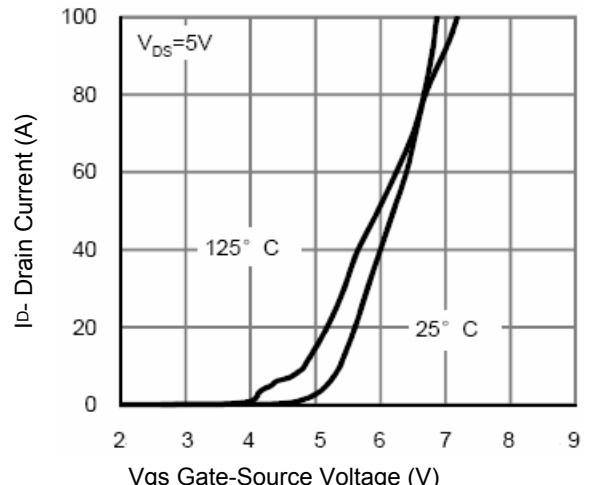


Figure 2. Transfer Characteristics

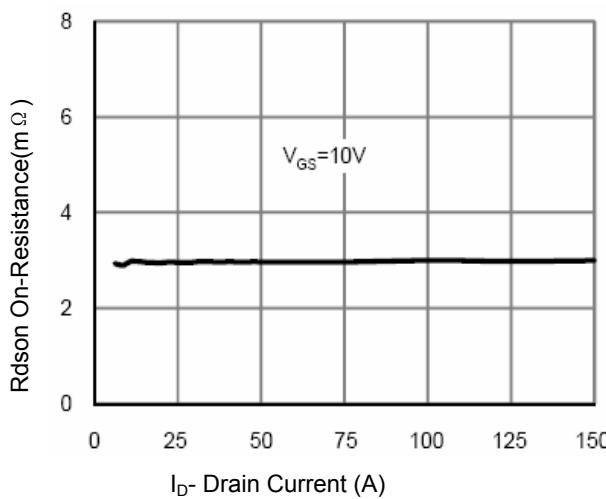


Figure 3. Rdson- Drain Current

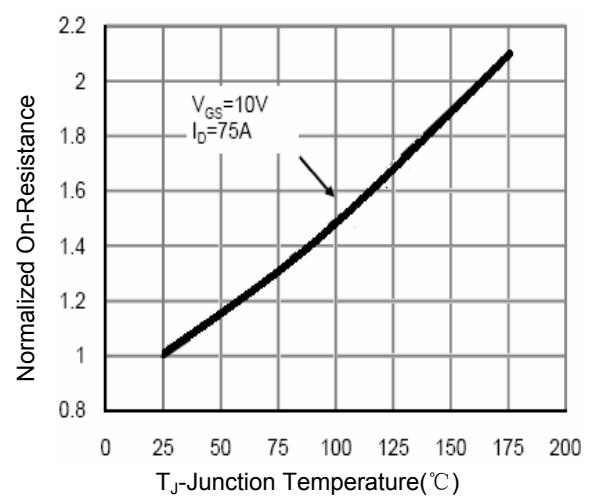


Figure 4. Rdson-JunctionTemperature

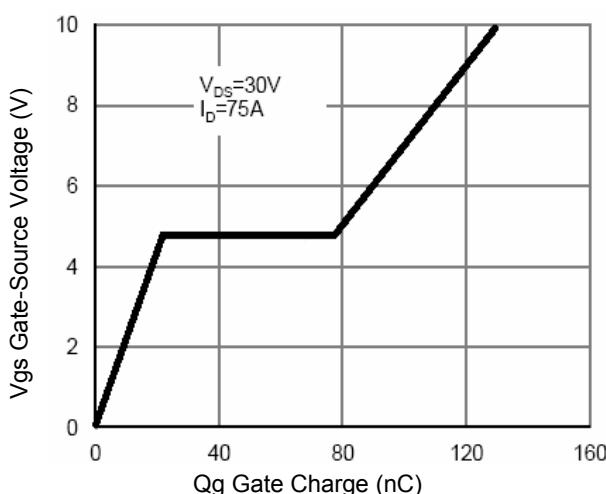


Figure 5. Gate Charge

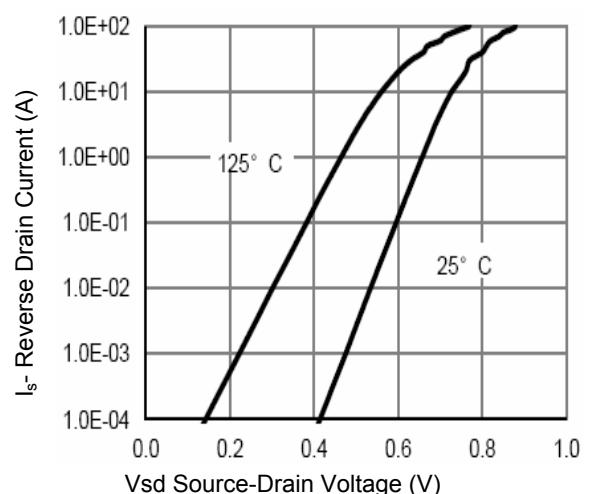


Figure 6. Source- Drain Diode Forward

Typical Electrical and Thermal Characteristic Curves

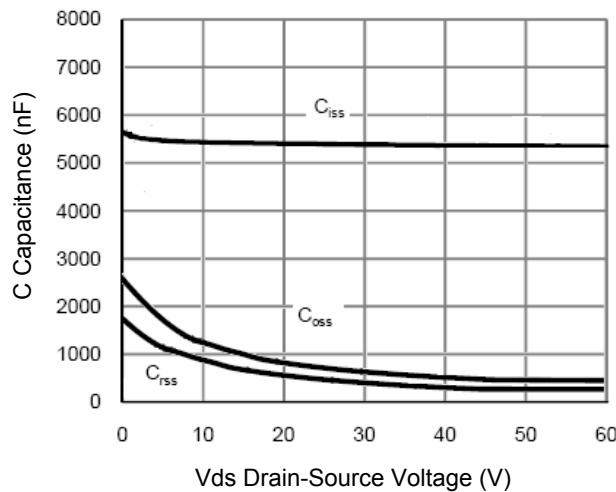


Figure 7. Capacitance vs Vds

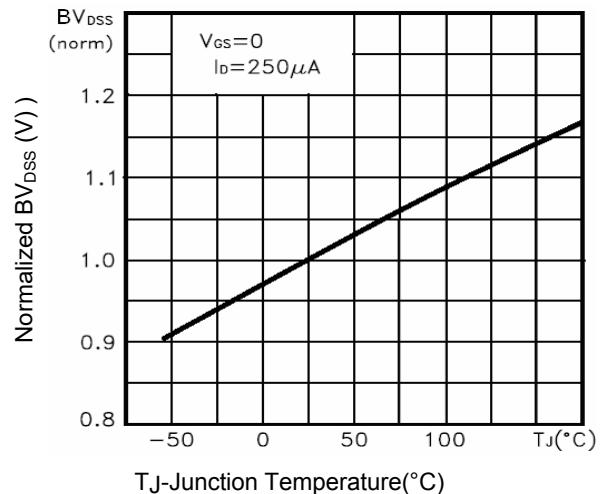


Figure 8. BV_{dss} vs Junction Temperature

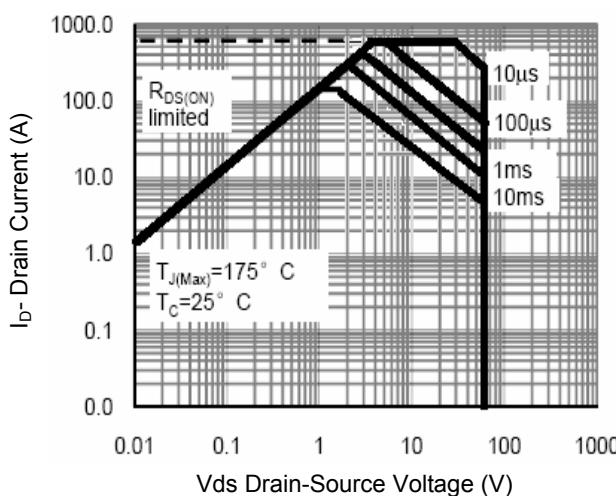


Figure 9. Safe Operation Area

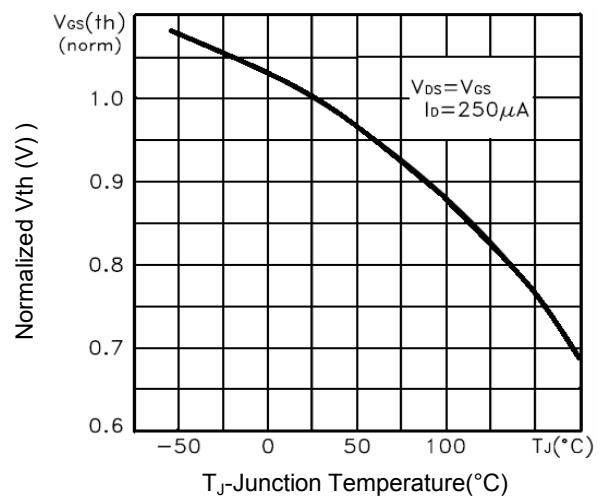


Figure 10. V_{th} vs Junction Temperature

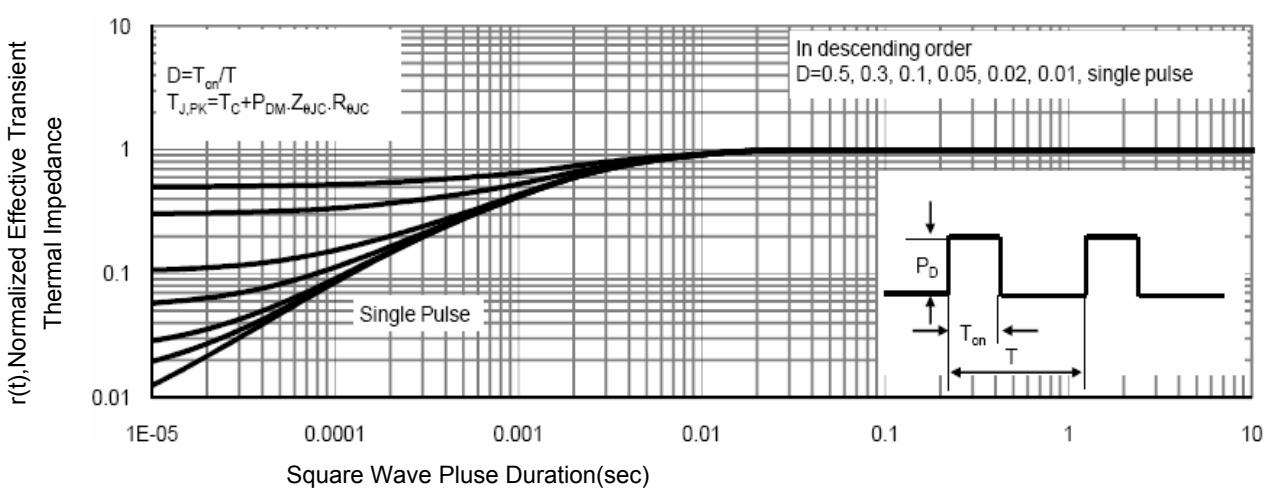


Figure 11. Normalized Maximum Transient Thermal Impedance

Typical Electrical and Thermal Characteristic Curves

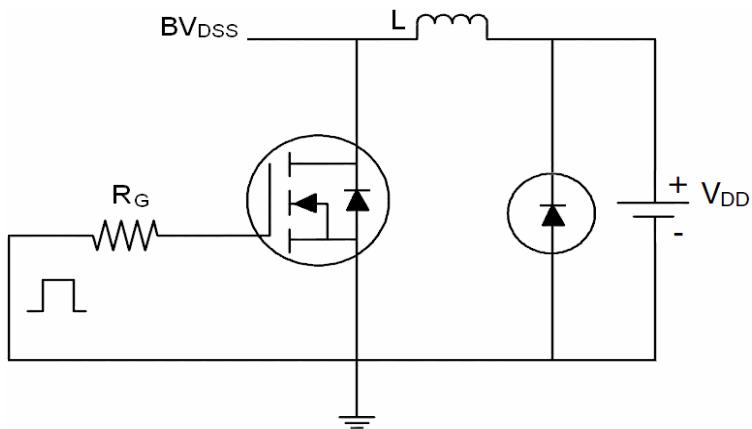


Figure 12. E_{AS} Test Circuit

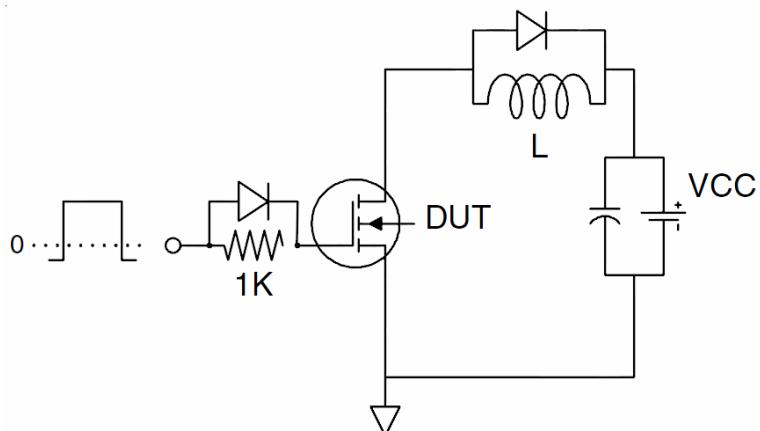


Figure 13. Gate Charge Test Circuit

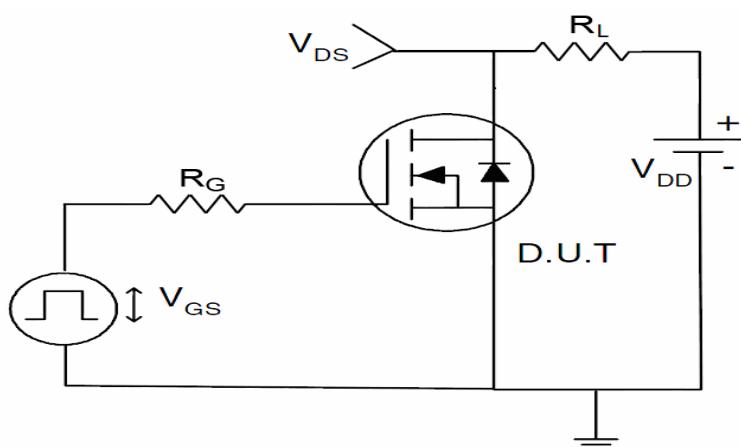
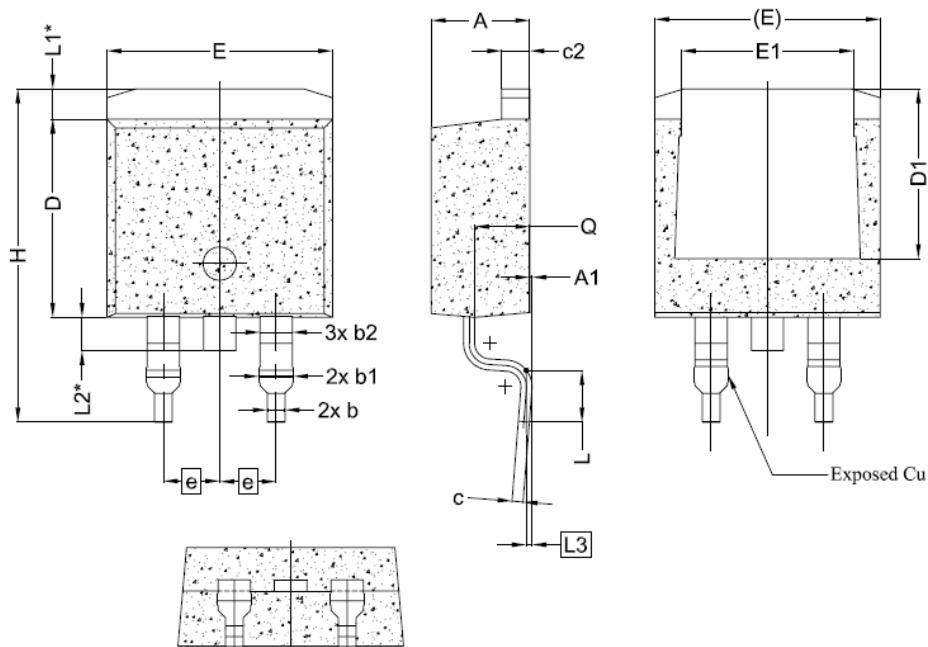


Figure 14. Switch Time Test Circuit

Package Outline Dimensions (TO-263/D²PAK)



| Symbol | Dimensions In Millimeters | | |
|--------|---------------------------|-------|-------|
| | Min. | Nom. | Max. |
| A | 4.24 | 4.44 | 4.64 |
| A1 | 0.00 | 0.10 | 0.25 |
| b | 0.70 | 0.80 | 0.90 |
| b1 | 1.20 | 1.55 | 1.75 |
| b2 | 1.20 | 1.45 | 1.70 |
| c | 0.40 | 0.50 | 0.60 |
| c2 | 1.15 | 1.27 | 1.40 |
| D | 8.82 | 8.92 | 9.02 |
| D1 | 6.86 | 7.65 | - |
| E | 9.96 | 10.16 | 10.36 |
| E1 | 6.89 | 7.77 | 7.89 |
| e | 2.54BS | | |
| H | 14.61 | 15.00 | 15.88 |
| L | 1.78 | 2.32 | 2.79 |
| L1 | 1.36 REF. | | |
| L2 | 1.50 REF. | | |
| L3 | 0.25 BSC | | |
| Q | 2.30 | 2.48 | 2.70 |